Product data sheet

1. General description

40A 650V Trench Fieldstop IGBT with antiparallel diode in TO247 pacakge. The WeEn WG40N65DFW uses advanced field stop technology. This device is ideal for Motor control and PFC.



2. Features and benefits

- · Advanced Trench Fieldstop technology
- · Very soft, fast recovery anti-parallel diode
- High speed switching
- EMI Improved Design

3. Applications

- Motor control
- PFC

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter		Notes		Value		Unit
V _{CE}	Collector-emitter voltage, T _j ≥ 25 °C			650			V
I _c	DC collector current, limited by $T_{j(max)}$ $T_C = 100 ^{\circ}C$				40		Α
Symbol	Parameter Conditions		Notes	Min	Тур	Max	Unit
Static characteristics							
V _{CE(sat)}	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}; I_{C} = 40 \text{ A}; T_{j} = 25 \text{ °C}$		-	1.5	1.95	V

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		.0
2	С	collector		
3	Е	emitter		(__
mb	С	mounting base; connected to collector		G E sym200

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WG40N65DFW	TO247	WG40N65DFWQ	Tube	30	SOT429	25-Mar-2013

7. Marking

Table 4. Marking codes

Type number	Marking codes
WG40N65DFW	WG40N 65DFW

8. Limiting values

Table 5. Limiting values

Symbol	Parameter	Notes	Value	Unit
V _{CE}	Collector-emitter voltage, T _j ≥ 25 °C		650	V
I _C	DC collector current, limited by $T_{j(max)}$ T_{c} = 25 °C T_{c} = 100 °C		85 40	А
I _{C(puls)}	Pulsed collector current, t_p limited by $T_{j(max)}$		120	А
-	Turn off safe operating area $V_{CE} \le 600 \text{ V}, T_j \le 125 ^{\circ}\text{C}, t_p = 1 \mu\text{s}$		120	Α
I _F	Diode forward current, limited by $T_{j(max)}$ T_{C} = 25 °C T_{C} = 100 °C		35 17	А
I _{Fpuls}	Diode pulsed current, t _p limited by T _{j(max)}		40	Α
V_{GE}	Gate-emitter voltage		±20	V
P _{tot}	Power dissipation $T_C = 25 ^{\circ}\text{C}$ Power dissipation $T_C = 100 ^{\circ}\text{C}$		313 125	W
T _{stg}	Storage temperature		-55 to 150	°C
T _j	Operating junction temperature		-55 to 150	°C
-	Peak soldering temperture		260	°C
M	Mounting Torque with washer		0.55	Nm

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-c)}	IGBT thermal resistance from junction to case			-	0.4	-	K/W
R _{th(j-c)}	Diode thermal resistance from junction to case			-	2.3	-	K/W
R _{th(j-a)}	thermal resistance from junction to ambient			-	40	-	K/W

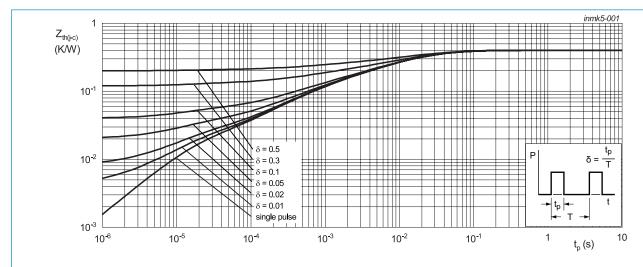


Fig. 1. Transient thermal impedance from junction to case as a function of pulse duration; IGBT

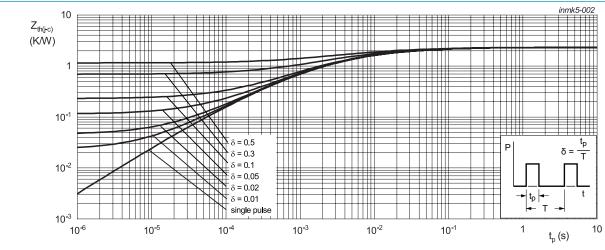


Fig. 2. Transient thermal impedance from junction to case as a function of pulse duration; Diode

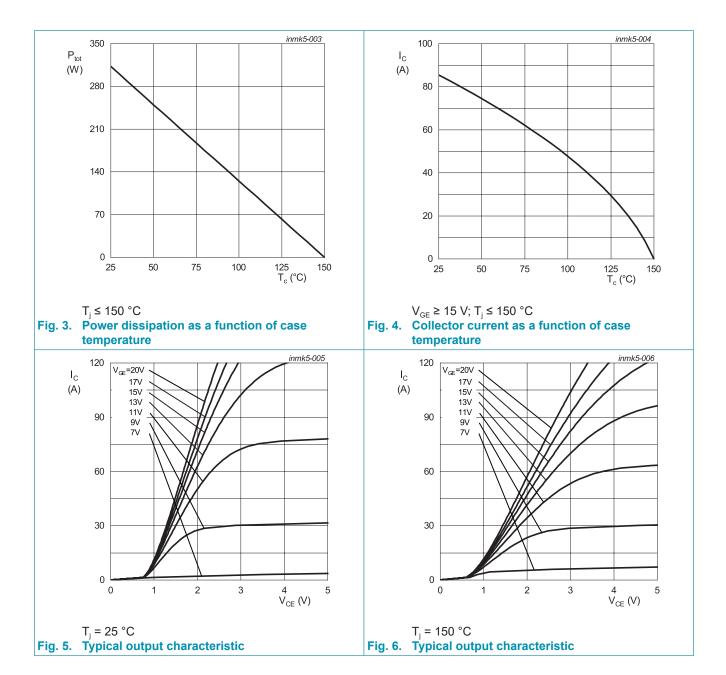
10. Characteristics

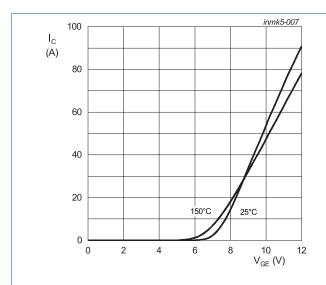
Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	racteristics						
BV_CES	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}; I_{C} = 50 \mu\text{A}$		650	-	-	V
$V_{\text{CE(sat)}}$	Collector-emitter saturation	V_{GE} = 15 V; I_{C} = 40 A; T_{j} = 25 °C		-	1.5	1.95	V
	voltage	V_{GE} = 15 V; I_{C} = 40 A; T_{j} = 150 °C		-	1.8	-	•
V _F Diode forw	Diode forward voltage	$V_{GE} = 0 \text{ V}; I_F = 10 \text{ A}; T_j = 25 ^{\circ}\text{C}$		-	1.24	-	V
		$V_{GE} = 0 \text{ V}; I_F = 10 \text{ A}; T_j = 150 ^{\circ}\text{C}$		-	1.1	-	V
$V_{\text{GE(th)}}$	Gate-emitter threhold voltage	$I_C = 1 \text{ mA}; V_{CE} = V_{GE}$		4.2	5.2	6.2	V
I _{CES}	Zero gate voltage collector	$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 25 \text{ °C}$		-	-	10 μΑ	μA
	current	$V_{CE} = 650 \text{ V}; V_{GE} = 0 \text{ V}; T_j = 150 \text{ °C}$		-	-		mA
g _{fs}	Transconductance	$V_{CE} = 20 \text{ V}; I_{C} = 40 \text{ A}$		-	20	-	S
Dynamic	characteristics						
C _{ies}	Input capacitance	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz};$		-	1595	-	pF
C _{oes}	Output capacitance	T _j = 25 °C		-	79	-	pF
C _{res}	Reverse transfer capacitance			-	49	-	pF
Q_{G}	Gate charge	V_{CC} = 520 V; I_{C} = 40 A; V_{GE} = 0 to 15 V; T_{I} = 25 °C		-	173	-	nC

11. Switching Characteristics

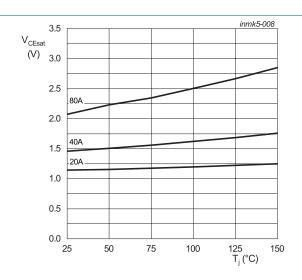
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
IGBT cha	racteristics						
$t_{d(on)}$	Turn-on delay time	T _j = 25 °C;		-	36	-	nS
t _r	Rise time	$V_{CC} = 400 \text{ V}; I_C = 40 \text{ A}; V_{GE} = 15 \text{V} / 0 \text{V};$ $R_G = 10 \Omega$		-	58	-	nS
$t_{d(off)}$	Turn-off delay time			-	250	-	nS
t _f	Fall time			-	49	-	nS
E _{on}	Turn-on energy			-	1.7	-	mJ
E _{off}	Turn-off energy			-	1	-	mJ
E _{ts}	Total switching energy			-	2.7	-	mJ
t _{d(on)}	Turn-on delay time	$T_{J} = 150 ^{\circ}\text{C};$ $V_{CC} = 400 \text{V}; I_{C} = 40 \text{A}; V_{GE} = 15 \text{V} / 0 \text{V};$ $R_{G} = 10 \Omega$		-	35	-	nS
t _r	Rise time			-	60	-	nS
$t_{\text{d(off)}}$	Turn-off delay time			-	278	-	nS
t _f	Fall time			-	100	-	nS
E _{on}	Turn-on energy			-	2.4	-	mJ
E _{off}	Turn-off energy			-	1.4	-	mJ
E _{ts}	Total switching energy			-	3.8	-	mJ
Diode cha	aracteristics		'		'		
t _{rr}	Reverse recovery time	T _j = 25 °C;		-	81	-	nS
Q_r	Reverse recovery charge	$\dot{V}_{R} = 400 \text{ V}; I_{F} = 30 \text{ A}; dI_{F}/dt = 500 \text{ A/us}$		-	646	-	nC
I _{RM}	Reverse recovery peak current			-	16	-	А
t _{rr}	Reverse recovery time	$T_j = 150 ^{\circ}\text{C};$ $V_R = 400 \text{V}; I_F = 30 \text{A}; dI_F/dt = 500 \text{A/us}$		-	136	-	nS
Q _r	Reverse recovery charge			-	1628	-	nC
I _{RM}	Reverse recovery peak current			-	24	-	А





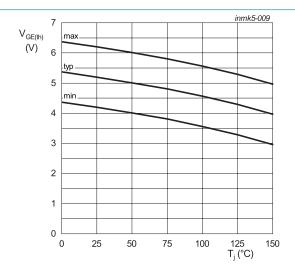
 $V_{CE} = 20 \text{ V}$

Fig. 7. Typical transfer characteristic



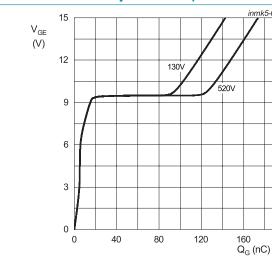
 $V_{GE} = 15 V$

Fig. 8. Typical collector-emitter saturation voltage as a function of junction temperature



 $I_c = 1 \text{ mA}$ Fig. 9. Gate-emitter threshold voltage as a function

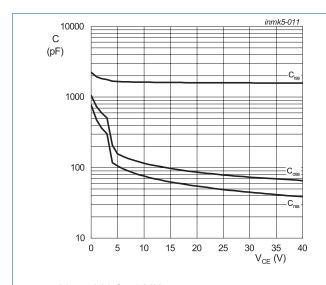
of junction temperature



 $I_{c} = 40 \text{ A}$

Fig. 10. Typical gate charge

200



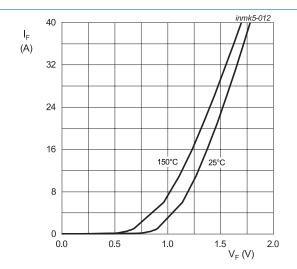
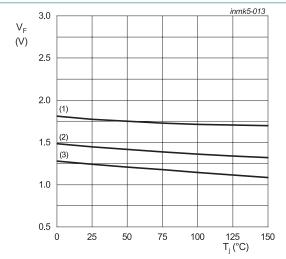
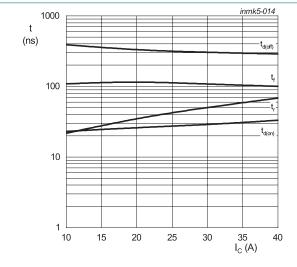


Fig. 12. Typical diode forward current as a function of forward voltage

 $\label{eq:VGE} V_{GE} = 0 \ V; \ f = 1 \ MHz$ Fig. 11. Typical capacitance as a function of collector-emitter voltage





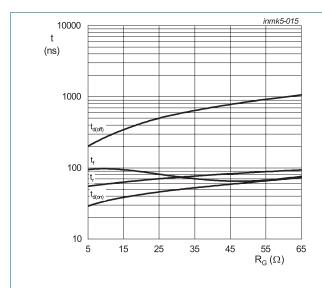
(1) $I_F = 40 A$ (2) $I_F = 20 A$

(3) $I_F = 10 A$

 R_{g} = 10 $\Omega;$ V_{GE} = 15V/0V; T_{j} = 150 °C; V_{CE} = 400 V; inductive load

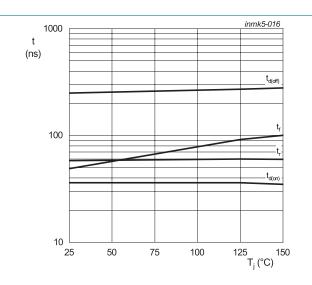
Fig. 13. Typical diode forward voltage as a function of junction temperature

Fig. 14. Typical switching times as a function of collector current

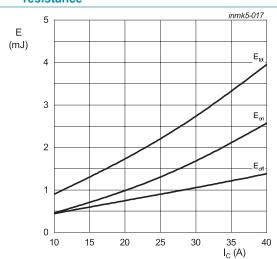


 $\rm I_{C}$ = 40 A; $\rm V_{GE}$ = 15V/0V; $\rm T_{j}$ = 150 °C; $\rm V_{CE}$ = 400 V; inductive load

Fig. 15. Typical switching times as a function of gate resistance

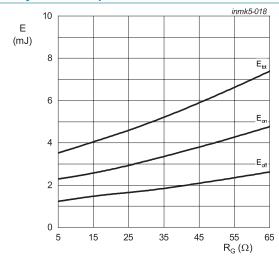


$$\begin{split} I_{\text{C}} = 40 \text{ A; } V_{\text{GE}} = 15 \text{V/0V; } R_{\text{g}} = 10 \text{ }\Omega; \\ V_{\text{CE}} = 400 \text{ V; inductive load} \end{split}$$
 Fig. 16. Typical switching times as a function of junction temperature



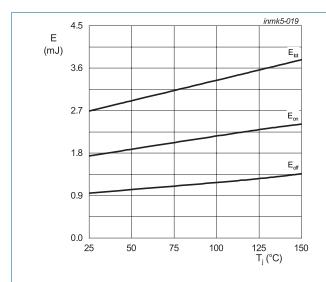
 R_g = 10 Ω ; V_{GE} = 15V/0V; T_j = 150 °C; V_{CE} = 400 V; inductive load

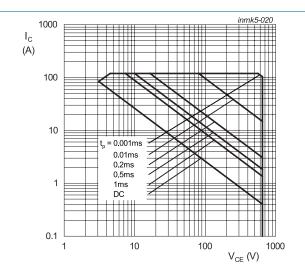
Fig. 17. Typical switching energy losses as a function of collector current



 I_{C} = 40 A; V_{GE} = 15V/0V; T_{j} = 150 °C; V_{CE} = 400 V; inductive load

Fig. 18. Typical switching energy losses as a function of gate resistance





 I_{C} = 40 A; V_{GE} = 15V/0V; R_{g} = 10 $\Omega;$ V_{CE} = 400 V; inductive load

Fig. 20. Forward bias safe operating area

Fig. 19. Typical switching energy losses as a function of junction temperature

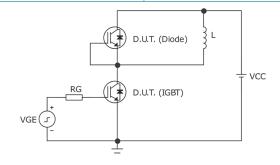


Fig. 21. Test circuit for inductive load switching

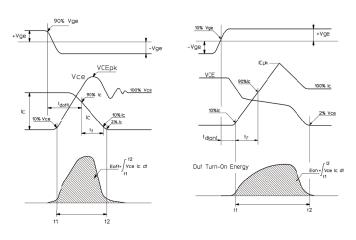
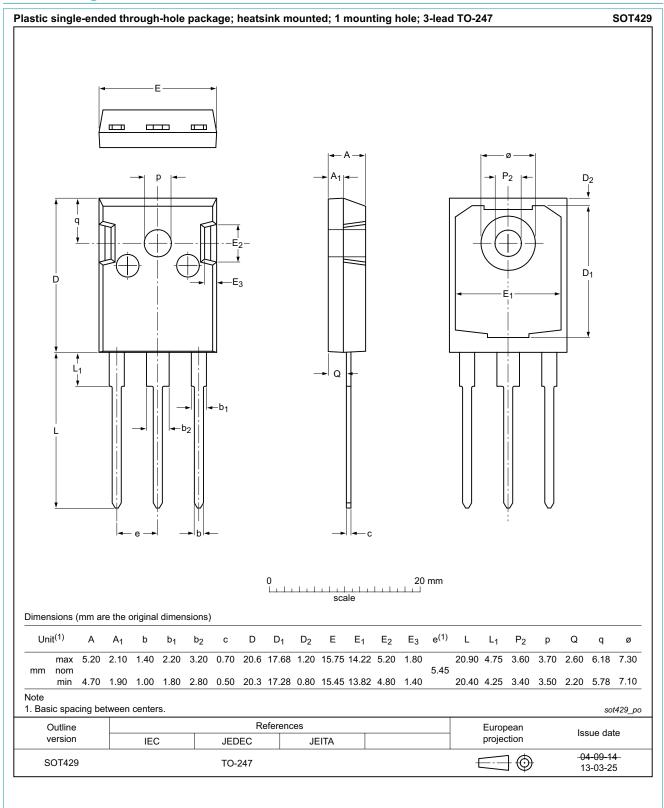


Fig. 22. Definition of switching times and losses

12. Package outline



13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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